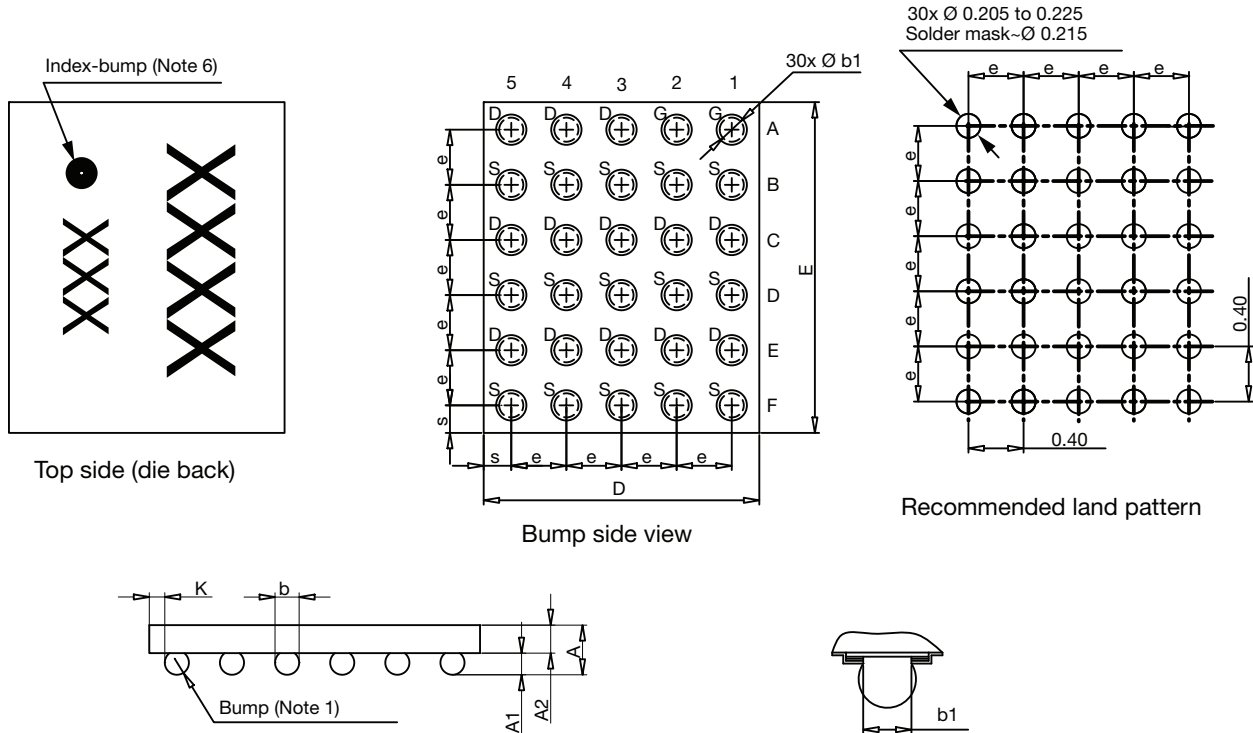


## MICRO FOOT<sup>®</sup>: 30-Bumps (2.4 mm x 2 mm, 0.4 mm Pitch, 0.184 mm Bump Height)


**Notes**

1. Bumps are 95.5/3.8/0.7 Sn/Ag/Cu.
2. Backside surface is coated with a Ti/Ni/Ag layer.
3. Non-solder mask defined copper landing pad.
4. Laser marks on the silicon die back.
5. "b1" is the diameter of the solderable substrate surface, defined by an opening in the solder resist layer solder mask defined.
6. • is the location of pin 1

DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.328	0.365	0.402	0.0129	0.0144	0.0158
A1	0.136	0.160	0.184	0.0054	0.0063	0.0072
A2	0.192	0.205	0.218	0.0076	0.0081	0.0086
b	0.200	0.220	0.240	0.0079	0.0087	0.0094
b1		0.175			0.0069	
e		0.400			0.0157	
s	0.160	0.180	0.200	0.0063	0.0071	0.0079
D	1.920	1.960	2.000	0.0756	0.0772	0.0787
E	2.320	2.360	2.400	0.0913	0.0929	0.0945
K	0.040	0.070	0.100	0.0016	0.0028	0.0039

**Note**

- Use millimeters as the primary measurement.

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